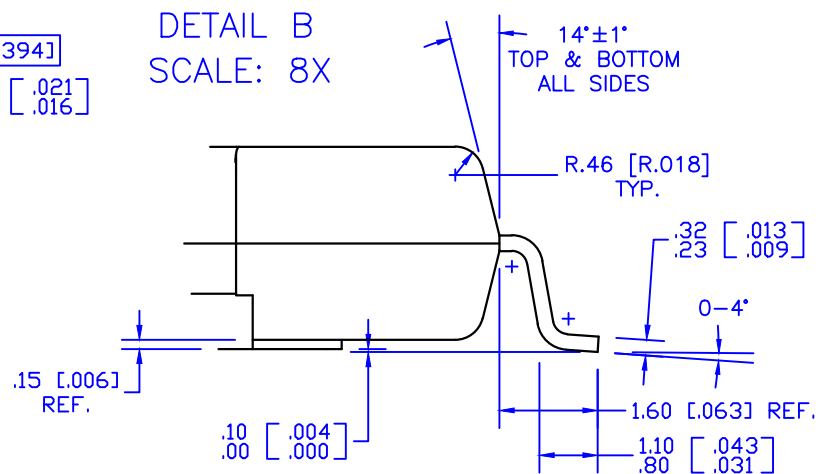
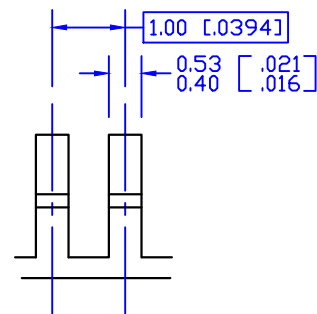


Surface Mount Layout



NOTES:

- Dimensions are millimeters & [inches].
- Bracketed alternate units are for reference only.
- Dimple on lid & ESD triangle denote pin 1.
- Pins & Heat Slug: CDA 194 copper with bismuth solder finish
- Mold compound: MP-8000AN epoxy
- Package weight: .086 oz. [2.44 g]
- Suggested surface mount layout for reference only.

TOLERANCES - UNLESS OTHERWISE SPECIFIED
.XX = ±0.01 [0.254]
.XXX = ±0.005 [0.127]
ANG. = ±5°



TITLE: JEDEC MO-166, 24-pin PSOP				MODEL:
SUBJECT: PACKAGE OUTLINE				DF
ENGINEER: J.MUTZ	DRAWN BY: J.FAY	DCA: 16322	SH: 1 OF 1	FILENAME: DF
REV: F	DATE: 05AUG16			

DF	F	05AUG16
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